L Number	Hits	Search Text	DB	Time stamp
7	518	(257/59, 72, 762, 751, "753").ccls. and @py>2001	USPAT; US-PGPUB;	2002/11/15
		CP1, 2001	EPO; JPO; DERWENT; IBM_TDB	
	523	(438/149, 151, 157, 163, 161, "166").ccls. and @py>2001	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/11/15 10:43
9	2349	(349/42-45, "116").ccls.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/11/15 10:43
10	5862	(438/30, 149-166).ccls.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/11/15 10:45
11	5361	(257/59-72, 762, 751, "753").ccls.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/11/15 10:46
12	12862	((349/42-45, "116").ccls.) or ((438/30, 149-166).ccls.) or ((257/59-72, 762, 751, "753").ccls.)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/15 10:47
13	301	<pre>(((349/42-45, "116").ccls.) or ((438/30, 149-166).ccls.) or ((257/59-72, 762, 751, "753").ccls.)) and ((cu or copper) with (Ti or titanium)) and (display or TFT or TFTs or (thin adj film adj transistor\$1))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15
14	4054	((cu or copper) with (Ti or titanium)) and (display or TFT or TFTs or (thin adj film adj transistor\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/15 14:08
15	1252	<pre>(((cu or copper) with (Ti or titanium)) and (display or TFT or TFTs or (thin adj film adj transistor\$1))) and (TiO\$6 or ((Ti or Titanium) near oxide))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 15:38
16	20	<pre>(((cu or copper) with (Ti or titanium)) and (display or TFT or TFTs or (thin adj film adj transistor\$1))) and ((corrosi\$4 or barrier or adhens\$4) with (TiO\$6 or ((Ti or Titanium) near oxide)))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15
17	12	(gate with (cu or copper)) and ((corrosi\$4 or barrier or adhens\$4) with (TiO\$6 or ((Ti or Titanium) near oxide)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/15
18	1	JP10153788\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/15 13:41
19	2	10153788\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/15 13:42

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		-		
20	2	"3302894"	USPAT; US-PGPUB;	2002/11/15
			EPO; JPO;	
			DERWENT; IBM_TDB	
21	10	((cu or copper) near2 (wiring or gate or wire)) with (Ti or TiO\$5) with	USPAT; US-PGPUB;	2002/11/15 14:38
		adhesion	EPO; JPO;	11.30
			DERWENT; IBM TDB	
22	238	((cu or copper) near2 (wiring or gate or wire)) with (Ti or TiO\$5)	USPĀT; US-PGPUB;	2002/11/15 14:04
	}	of wife,, with (if of 11005)	EPO; JPO;	11.01
			DERWENT; IBM TDB	
23	19	((cu or copper) near2 (wiring or gate or wire)) and (Ti with TiO\$5)	USPAT; US-PGPUB;	2002/11/15 14:07
		of wife)) and (if with 11033)	EPO; JPO;	14.07
			DERWENT; IBM TDB	
24	30922	((cu or copper) near2 (wiring or gate	USPAT;	2002/11/15
		or wire))	US-PGPUB; EPO; JPO;	14:33
			DERWENT; IBM TDB	
25	2812	(((cu or copper) near2 (wiring or gate	USPAT;	2002/11/15
		or wire))) and (display or TFT or TFTs or (thin adj film adj transistor\$1))	US-PGPUB; EPO; JPO;	14:08
			DERWENT; IBM TDB	
26	394	((((cu or copper) near2 (wiring or gate	USPAT;	2002/11/15
		or wire))·) and (display or TFT or TFTs or (thin adj film adj transistor\$1)))	US-PGPUB; EPO; JPO;	14:09
		and (Ti or titanium or TIO\$6)	DERWENT; IBM TDB	:
27	10	(((cu or copper) near2 (wiring or gate	USPAT;	2002/11/15
		or wire))) and ((Ti or Titanium) with anodiz\$5)	US-PGPUB; EPO; JPO;	14:34
			DERWENT; IBM TDB	
28	280	(cu or copper) and ((Ti or Titanium) with anodiz\$5)	USPAT; US-PGPUB;	2002/11/15 14:35
		with anodizas)	EPO; JPO;	14:35
			DERWENT; IBM TDB	
29	126	((cu or copper) and ((Ti or Titanium)	USPAT; US-PGPUB;	2002/11/15 14:36
		<pre>with anodiz\$5)) and (gate or interconnect\$5 or wir\$5)</pre>	EPO; JPO;	14:36
			DERWENT; IBM TDB	
30	1147	((cu or copper) near2 (wiring or gate	USPAT; US-PGPUB;	2002/11/15 14:52
		or wire)) and (TiO\$5 or ((Ti or Titanium) with oxid\$7))	EPO; JPO;	±7.J2
			DERWENT; IBM TDB	
31	1148	((cu or copper) near2 (wiring or gate or wire)) and (TiO\$5 or ((Ti or	USPAT; US-PGPUB;	2002/11/15 14:53
		Titanium) with (oxide\$1 or oxidat\$4)))	EPO; JPO;	11.00
			DERWENT; IBM TDB	
32	125	(((cu or copper) near2 (wiring or gate or wire)) and (TiO\$5 or ((Ti or	USPĀT; US-PGPUB;	2002/11/15 14:45
		Titanium) with (oxide\$1 or oxidat\$4))))	EPO; JPO;	11.30
		and gate	DERWENT; IBM_TDB	
33	1661	<pre>gate with (TiO\$5 or ((Ti or Titanium) with oxid\$7))</pre>	USPĀT; US-PGPUB;	2002/11/15 15:35
		WICH ONIGYTT	EPO; JPO;	20.00
			DERWENT; IBM_TDB	

			_	
34	2269		USPAT;	2002/11/15
		((Ti or Titanium) with (oxide\$1 or	US-PGPUB;	14:54
		oxidat\$4)))	EPO; JPO;)
			DERWENT;	
			IBM TDB	<u> </u>
35	205	((cu or copper) and gate and (TiO\$5 or	USPAT;	2002/11/15
		((Ti or Titanium) with (oxide\$1 or	US-PGPUB;	15:28
		oxidat\$4)))) and (((349/42-45,	EPO; JPO;)
		"116").ccls.) or ((438/30,	DERWENT;	1
-		149-166).ccls.) or ((257/59-72, 762,	IBM TDB	1
		751, "753").ccls.))	_	
36	1364	gate with anodic	USPAT;	2002/11/15
			US-PGPUB;	15:29
			EPO; JPO;	
			DERWENT;	
			IBM_TDB)
37	79	(gate with anodic) and (gate with	USPAT;	2002/11/15
		(TiO\$5 or ((Ti or Titanium) with	US-PGPUB;	15:29
		oxid\$7)))	EPO; JPO;	1
			DERWENT;	j
			IBM_TDB	
38	68	3 (USPAT;	2002/11/15
		with oxid\$7)) with (covered or coated)	US-PGPUB;	15:37
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
39	2580	438/158.ccls.	USPAT;	2002/11/15
			US-PGPUB;	15:47
			EPO; JPO;	}
			DERWENT;	
4.0		1,00,000	IBM_TDB	
40	31	438/158.ccls. and (TiO\$6 or ((Ti or	USPAT;	2002/11/15
		Titanium) near oxide))	US-PGPUB;	15:56
			EPO; JPO;]
			DERWENT;	
4.1		5334544 ****	IBM_TDB	0000400405
41	11	5334544.URPN.	USPAT	2002/11/15
42] 37	439/159 male and (make with (G), and	***********	15:41
76	27	438/158.ccls. and (gate with (Cu or	USPAT;	2002/11/15
		copper))	US-PGPUB;	15:53
]		EPO; JPO; DERWENT;	
			IBM TDB	
43	56	"5166085"	USPAT;	2002/11/15
30	"	3100003	US-PGPUB;	15:54
			EPO; JPO;	10.01
			DERWENT;	
			IBM TDB	
44	64	438/158.ccls. and (TiO\$6 or ((Ti or	USPAT;	2002/11/15
- -	"	Titanium) with oxid\$5))	US-PGPUB;	15:57
l			EPO; JPO;	
ļ			DERWENT;	
l	i		IBM TDB	
45	33	(438/158.ccls. and (TiO\$6 or ((Ti or	USPAT;	2002/11/15
ļ		Titanium) with oxid\$5))) not	US-PGPUB;	15:57
		(438/158.ccls. and (TiO\$6 or ((Ti or	EPO; JPO;	
		Titanium) near oxide)))	DERWENT;	
ľ			IBM TDB	
_ !	9	((cu or copper) near2 (wiring or wire))	USPĀT;	2002/11/15
		with Tin with adhesion	US-PGPUB;	13:44
			EPO; JPO;	
			DERWENT;	
		,	IBM TDB	